



IEEE EDSSC 2020

The 16th IEEE International Conference on Electron Devices and Solid-State Circuits

June 3 - 5, 2020, City University of Hong Kong, Hong Kong, China

Conference website: <http://ieee-edssc.org>



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IEEE EDSSC 2020 is the 16th in a series of very successful conferences initiated by IEEE ED/SSC Hong Kong Chapter. EDSSC 2020 continues the EDSSC tradition as a multidisciplinary forum for the exchange of ideas, research results, and industry experience in the broad areas of electron devices and solid-state circuits and systems. The technical program includes invited talks by famous scientists and contributed papers. All accepted papers will be invited to submit to the IEEE Xplore database which will be indexed by EI Compendex

We invite contributions describing the latest scientific and technological results in subjects including but not limited to the following:

- 2D Materials and Devices
- Emerging Devices
- Energy Devices
- Device Reliability
- Display and Imager
- Memory Devices
- MEMS and Sensors
- Nano-electronics
- Organic Devices
- Oxides Electronics
- Perovskite Electronics
- Power Devices
- RF & Microwave Devices
- Quantum Devices
- Analog, Amplifier and Filter Circuits
- Biomedical Circuits
- Circuits for Internet-of-Things
- Circuits for Quantum Computing
- Circuits for Robotics and Automation
- Data Converters
- Digital, Memory and IO Circuits
- Hardware Security
- Processors, SoCs and Machine Learning Circuits
- Power Management Circuits
- RF & Microwave Circuits
- Sensor Interface Circuits
- Wireline and Optical Transceivers

Important Dates:

Submission Deadline of 2-page Paper: **Mar 20, 2020**

Acceptance Notification: April 20, 2020

Inquiry:

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